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ON Semiconductor®

FQB5N90

N-Channel QFET® MOSFET

900 V, 5.4 A, 2.3 Ω

Description

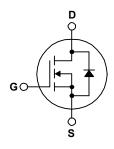
This N-Channel enhancement mode power MOSFET is • Low Gate Charge (Typ. 31 nC) produced using ON Semiconductor's proprietary planar • Low Crss (Typ. 13 pF) stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state • 100% Avalanche Tested resistance, and to provide superior switching performance

• RoHS Compliant and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 5.4 A, 900 V, $R_{DS(on)}$ = 2.3 Ω (Max.) @ V_{GS} = 10 V, $I_D = 2.7 A$





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

| Symbol | Parameter | | FQB5N90TM | Unit | |
|-----------------------------------|--|---------|-------------|------|--|
| V _{DSS} | Drain-Source Voltage | | 900 | V | |
| I _D | Drain Current - Continuous (T _C = 25°C) | | 5.4 | Α | |
| | - Continuous (T _C = 100°C) | | 3.42 | Α | |
| I _{DM} | Drain Current - Pulsed (| Note 1) | 21.6 | А | |
| V _{GSS} | Gate-Source Voltage | | ± 30 | V | |
| E _{AS} | Single Pulsed Avalanche Energy (| Note 2) | 660 | mJ | |
| I _{AR} | Avalanche Current (| Note 1) | 5.4 | Α | |
| E _{AR} | Repetitive Avalanche Energy (| Note 1) | 15.8 | mJ | |
| dv/dt | Peak Diode Recovery dv/dt (| Note 3) | 4.0 | V/ns | |
| P_{D} | Power Dissipation (T _A = 25°C) * | | 3.13 | W | |
| _ | Power Dissipation (T _C = 25°C) | | 158 | W | |
| | - Derate above 25°C | | 1.27 | W/°C | |
| T _J , T _{STG} | Operating and Storage Temperature Range | | -55 to +150 | °C | |
| T _L | Maximum lead temperature for soldering, 1/8" from case for 5 seconds | | 300 | °C | |

Thermal Characteristics

| Symbol | Parameter | FQB5N90TM | Unit |
|-----------------|---|-----------|------|
| R_{\thetaJC} | Thermal Resistance, Junction to Case, Max. | 0.79 | |
| В | Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max. | 62.5 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max. | 40 | |

Package Marking and Ordering Information

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|----------|---------------------|----------------|-----------|------------|-----------|
| FQB5N90TM | FQB5N90 | D ² -PAK | Tape and Reel | 330 mm | 24 mm | 800 units |

Electrical Characteristics

T_C = 25°C unless otherwise noted.

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|---|---|---|------|------|------------|------|
| Off Cha | aracteristics | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 900 | | | V |
| ΔBV _{DSS} / ΔT _J | Breakdown Voltage Temperature Coefficient | I _D = 250 μA, Referenced to 25°C | | 1.0 | | V/°C |
| I _{DSS} | Zara Cata Valtaria Dusin Comment | V _{DS} = 900 V, V _{GS} = 0 V | | | 10 | μΑ |
| | Zero Gate Voltage Drain Current | V _{DS} = 720 V, T _C = 125°C | | - | 100 | μΑ |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 30 V, V _{DS} = 0 V | | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} = -30 V, V _{DS} = 0 V | | | -100 | nA |
| | racteristics Gate Threshold Voltage | Vpc = Vcc | 3.0 | | 5.0 | V |
| V _{GS(th)} | Gate Threshold Voltage Static Drain-Source On-Resistance | $V_{DS} = V_{GS}, I_D = 250 \mu A$ $V_{GS} = 10 \text{ V}, I_D = 2.7 \text{ A}$ | 3.0 | 1.8 | 5.0 2.3 | ν Ω |
| 9 _{FS} | Forward Transconductance | V _{DS} = 50 V, I _D = 2.7 A | | 5.6 | | S |
| Dynam C _{iss} | ic Characteristics Input Capacitance | | | 1200 | 1550 | pF |
| Coss | Output Capacitance | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz | | 110 | 145 | pF |
| C _{rss} | Reverse Transfer Capacitance | 1 = 1.0 MHZ | | 13 | 17 | рF |
| | ing Characteristics | I | | | 1 | P. |
| t _{d(on)} | Turn-On Delay Time | V _{DD} = 450 V, I _D = 5.4 A, | | 28 | 65 | ns |
| t _r | Turn-On Rise Time | $R_{G} = 25 \Omega$ | | 65 | 140 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 65 | 140 | ns |
| t _f | Turn-Off Fall Time | (Note | 4) | 50 | 110 | ns |

| Drain-Source | Diode | Characteristics | and | Maximum | Ratings |
|--------------|-------|-------------------|------|----------|----------|
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| · · · · · · · · · · · · · · · · · · · | | | | | | | |
|---------------------------------------|---|--|--|------|------|----|--|
| I _S | Maximum Continuous Drain-Source Diode Forward Current | | | | 5.4 | Α | |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forward Current | | | | 21.6 | Α | |
| V _{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0 V, I _S = 5.4 A | | | 1.4 | V | |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0 V, I _S = 5.4 A, | | 610 | | ns | |
| Q _{rr} | Reverse Recovery Charge | dI _F / dt = 100 A/μs | | 5.26 | | μС | |

 V_{GS} = 10 V

 $V_{DS} = 720 \text{ V}, I_{D} = 5.4 \text{ A},$

31

7.2

15

(Note 4)

40

--

nC

nC

nC

Notes

Q_{gs}

 Q_{gd}

- ${\bf 1.}\ Repetitive\ rating: pulse-width\ limited\ by\ maximum\ junction\ temperature.$
- 2. L = 43 mH, I_{AS} = 5.4 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C.
- 3. I $_{SD} \leq$ 5.4 A, di/dt \leq 200 A/µs $\,$, $V_{DD} \leq$ BV $_{DSS,}$ starting $\,$ T $_{J}$ = 25°C.
- ${\bf 4.}\,{\bf Essentially}\,\,{\bf independent}\,\,{\bf of}\,\,{\bf operating}\,\,{\bf temperature}.$

Total Gate Charge

Gate-Source Charge

Gate-Drain Charge

Typical Characteristics

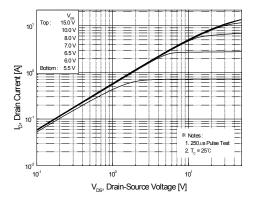


Figure 1. On-Region Characteristics

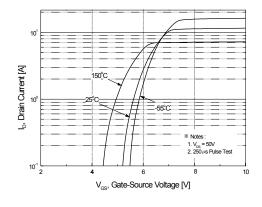


Figure 2. Transfer Characteristics

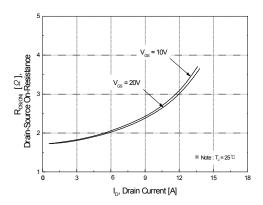


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

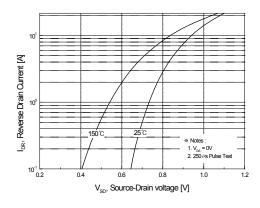


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

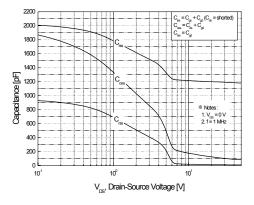


Figure 5. Capacitance Characteristics

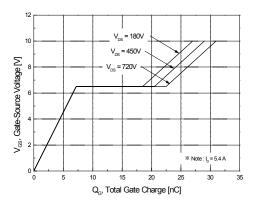
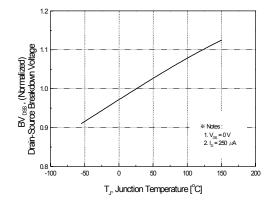


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

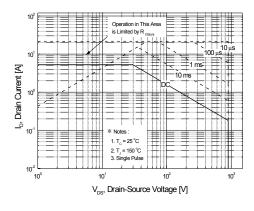


2.5 (normalized) 2.5 (n

3.0

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



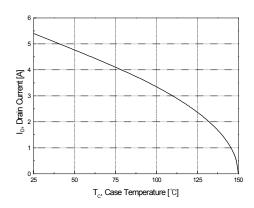


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

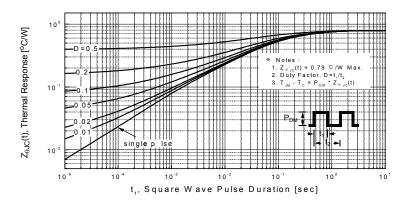


Figure 11. Transient Thermal Response Curve

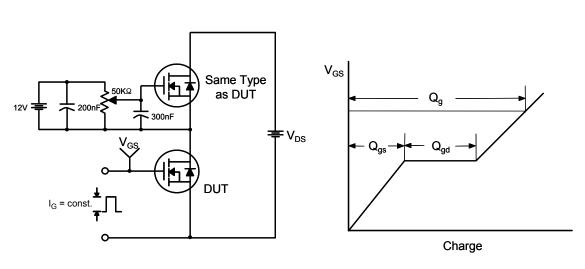


Figure 12. Gate Charge Test Circuit & Waveform

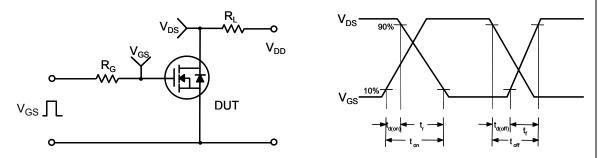


Figure 13. Resistive Switching Test Circuit & Waveforms

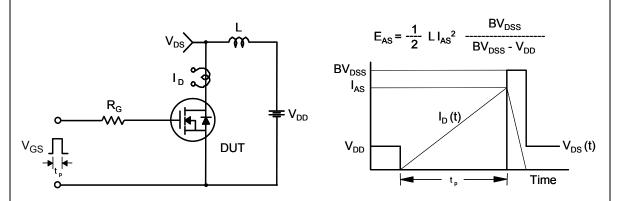


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

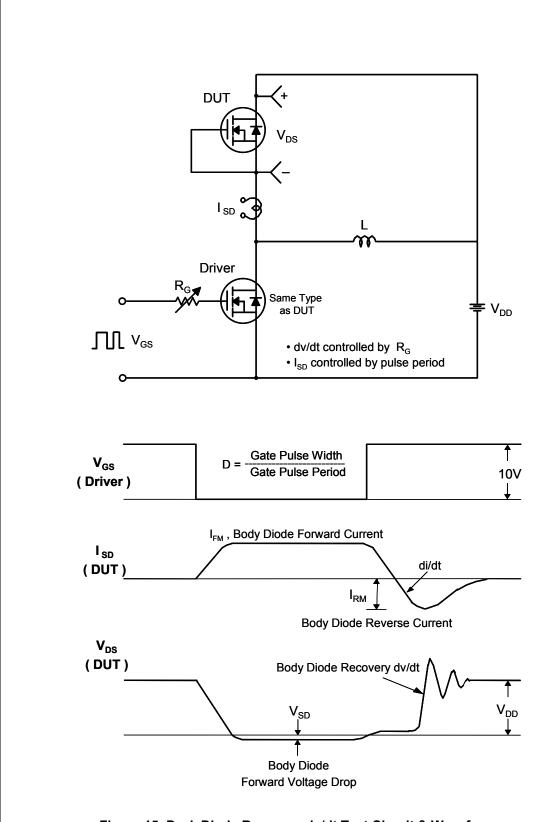


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

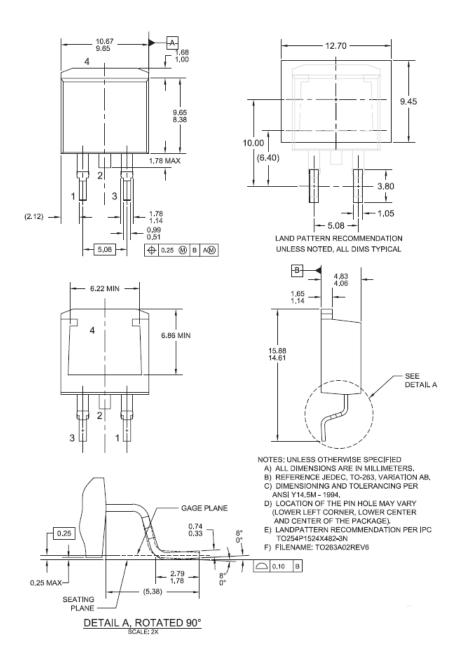


Figure 16. TO263 (D²PAK), Molded, 2-Lead, Surface Mount

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